

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims**

Claims 1-21 (canceled)

Claim 22 (new): A method of creating a bi-directional linear movement of a portion of a polishing pad disposed within a processing area for polishing of a workpiece comprising the steps of:

- creating bi-linear movement of a drive assembly; and
- contacting a backside of the polishing pad with a slide member coupled to the drive assembly to produce the bi-directional linear movement of the portion of the polishing pad within the processing area for polishing the workpiece.

Claim 23 (new) The method according to claim 22, wherein the polishing pad is disposed between a supply spool and a receive spool.

Claim 24 (new) The method according to claim 22 wherein the polishing pad passes through rollers disposed on the slide member.

Claim 25 (new) The method according to claim 22 wherein the step of contacting provides horizontal bi-directional linear movement of the slide member and horizontal bi-directional linear movement of the portion of the polishing pad within the processing area.

Claim 26 (new) The method according to claim 25, wherein the portion of the polishing pad moves horizontally at least two times as far as the slide member moves horizontally.

Claim 27 (new) The method according to claim 22, wherein the portion of the polishing pad moves a greater amount than the slide member.

Claim 28 (new) The method according to claim 22, wherein the step of contacting includes guiding the polishing pad on a plurality of rollers.

Claim 29 (new) The method according to claim 28, wherein the step of guiding includes physically contacting a back surface of the polishing pad with the plurality of rollers.

Claim 30 (new) The method according to claim 22, wherein the step of contacting the backside of the polishing pad includes passing the polishing pad through rollers disposed on the slide member.

Claim 31 (new) The method according to claim 22, wherein the step of contacting the backside of the polishing pad includes moving the drive assembly bi-directionally to produce the bi-directional linear movement of the portion of the polishing pad within the processing area.

Claim 32 (new) An apparatus for creating bi-directional linear motion within a predetermined area with a portion of a polishing pad corresponding to a processing area for polishing a workpiece comprising:

- a drive assembly;

- a slide member coupled to the drive assembly, the drive assembly configured to produce bi-linear movement of the slide member; and

- wherein the polishing pad is disposed through the slide member and bi-linear movement of the slide member creates a corresponding bi-linear movement of the portion of the polishing pad in the processing area for polishing the workpiece.

Claim 33 (new) The apparatus according to claim 32, wherein the drive assembly includes:

- a gear box coupled to a rotatable shaft and which contains another rotatable shaft;

- a crank coupled to the another rotatable shaft; and

- a link coupled between the rotatable shaft and the slide member.

Claim 34 (new) The apparatus according to claim 32, wherein the slide member includes a plurality of rollers.

Claim 35 (new) The apparatus according to claim 32, wherein the bi-linear movement of the slide member is horizontal.

Claim 36 (new) The apparatus according to claim 32, wherein the bi-linear movement of the portion of the polishing pad in the processing area is horizontal.

Claim 37 (new) The apparatus according to claim 32 further comprising:

- a supply spool;

- a receive spool; and

- a plurality of rollers configured to provide a pad path between a supply spool and a receive spool.

Claim 38 (new) The apparatus according to claim 37, wherein the plurality of rollers is configured to contact a back surface of the polishing pad.